PWB X-section Test Results

Supplier Name _____ PCB Supplier Name_____

Part Number _____ Date/Date Code of Manufacture _____

Evaluation Criteria	IPC-6012 Class 2 Requirements (Para 3.6 Thermal Stressed Coupon)	Results X plane	Results Y plane
Copper Voids	One void allowed per test specimen provided that additional microsection criteria of 3.6.2.2 are met. (Table 3-9)		
Plating Folds/Inclusions	Must maintain Cu thickness (Table 3-9)		
Burrs and Nodules	Allowed if minimum hole diameters are met (Table 3-9)		
Glass Fiber Extrusions	Allowed if minimum plating thickness is met (Para 3.6.2.11 and Table 3-9)		
Wicking, Max	100um max (.00394") (Table 3-9)		
Barrel/Corner cracks (Type E and F)	None allowed (Table 3-9)		
External foil cracks (Type B and D)	"D" and "B" cracks not allowed (Table 3-9)		
Innerlayer inclusions (inclusions at the interface between internal lands and through hole plating)	None allowed (Table 3-9)		
Innerlayer separations (separations at the interface between internal lands and the through hole plating)	None allowed (Table 3-9)		
Plating separations	None allowed (Table 3-9)		
Hole wall dielectric/plated barrel separation	Allowed provided dimensional and plating requirements are met (Table 3-9)		
Lifted pads (after thermal stress)	Allowed provided the finished boards met visual requirements (Table 3-9)		
Smear removal	Sufficient to remove resin debris (Para 3.6.2.7)		
Annular Ring and breakout (internal)	<90 degree breakout provided land and conductor junction is not reduced below acceptable limits (Table 3-8)		
Copper barrel thickness (avg)	20um min (.000787") (Table 3-2)		
Copper barrel thickness (min)	18um min (.000709") (Table 3-2)		
Dielectric thickness (min)	90um min (.00354") unless otherwise specified (Para 3.6.2.15)		